

Octal Buffer/Line Driver; 3-State

Features

- * 5V tolerant inputs/outputs for interfacing with 5V logic
- * Wide supply voltage range from 1.2V to 3.6V
- * CMOS low power consumption
- * Direct interface with TTL levels
- * Inputs accept voltages up to 5.5V
- * Specified from -40°C to +105°C

Packaging Information

- * SOIC-20
- * TSSOP-20
- * DHVQFN20

General Description

The HCR74LVC541 is an octal non-inverting buffer /line driver with 5V tolerant inputs and outputs.

The 3-state outputs are controlled by the output enable inputs ($\overline{OE1}$ and $\overline{OE2}$).

This device is fully specified for partial power-down applications using IOFF. The IOFF circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

Inputs can be driven from either 3.3V or 5.0V devices. When disabled, up to 5.5V can be applied to the outputs. These features allow the use of these devices as translators in mixed 3.3V and 5.0V applications.



Figure 1. Package Type of HCR74LVC541

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Pin Configuration

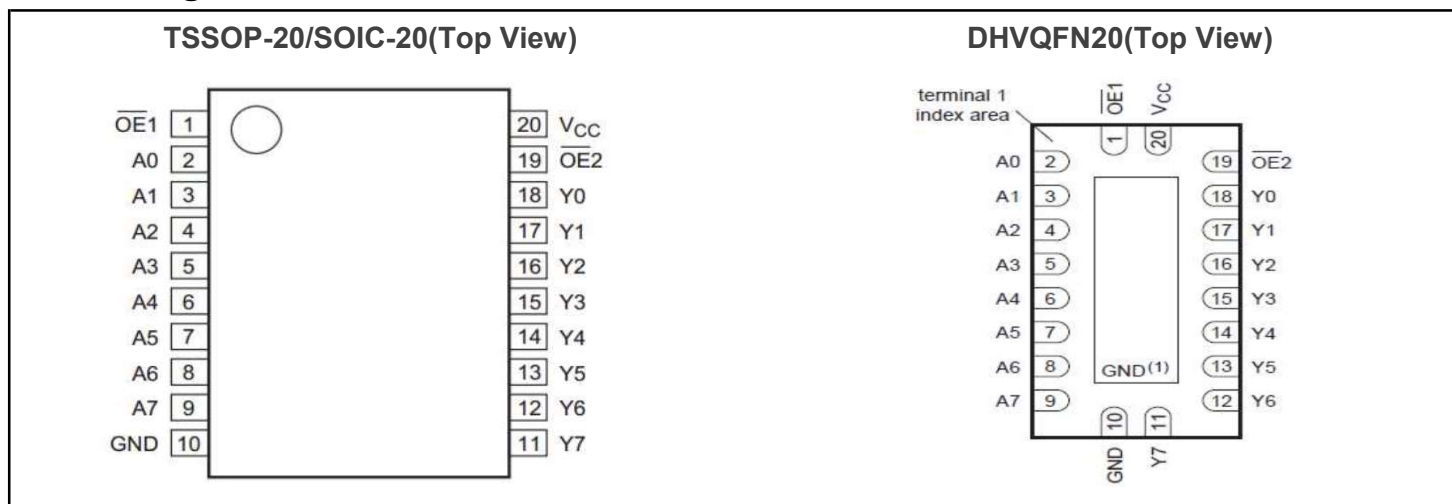


Figure 2. Pin Configuration of HCR74LVC541 (Top View)

Pin Function Table

Pin	NAME	FUNCTION
1	OE1	Output enable input (active LOW)
2	A0	Date Input
3	A1	Date Input
4	A2	Date Input
5	A3	Date Input
6	A4	Date Input
7	A5	Date Input
8	A6	Date Input
9	A7	Date Input
10	GND	Ground (0V)
11	Y7	bus output
12	Y6	bus output
13	Y5	bus output
14	Y4	bus output
15	Y3	bus output
16	Y2	bus output
17	Y1	bus output
18	Y0	bus output
19	OE2	Output enable input (active LOW)
20	V _{CC}	Supply voltage

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LOGIC SYMBOL

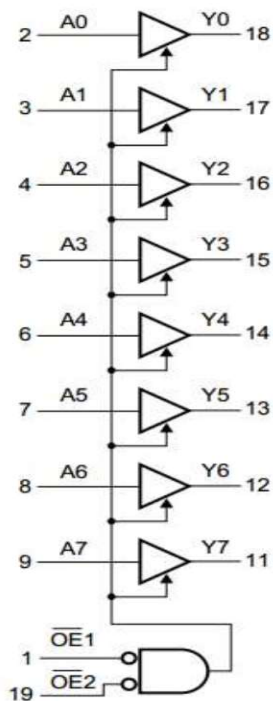


Figure 3. Logic Symbol

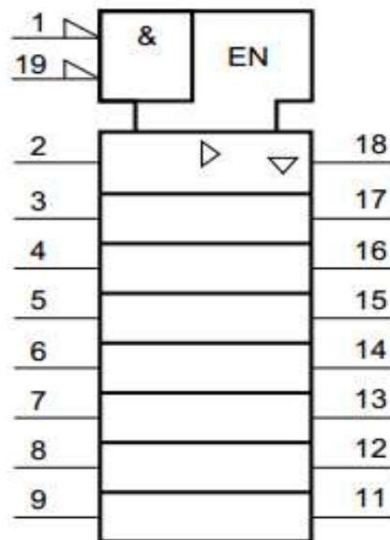


Figure 4. IEC Logic Symbol

Functional and Logic Diagram

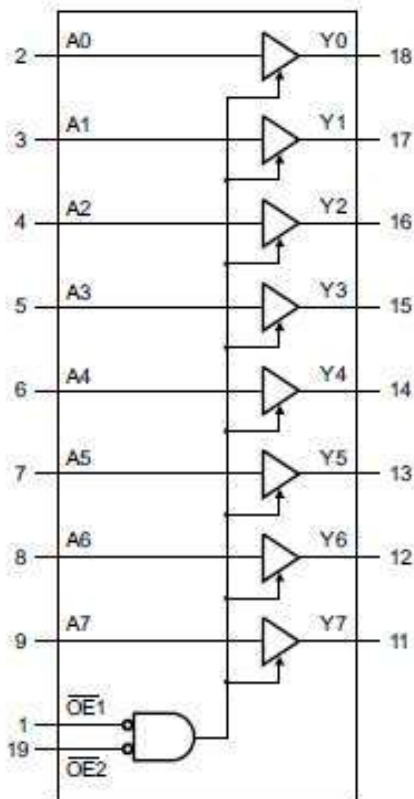


Figure 5. Functional Diagram

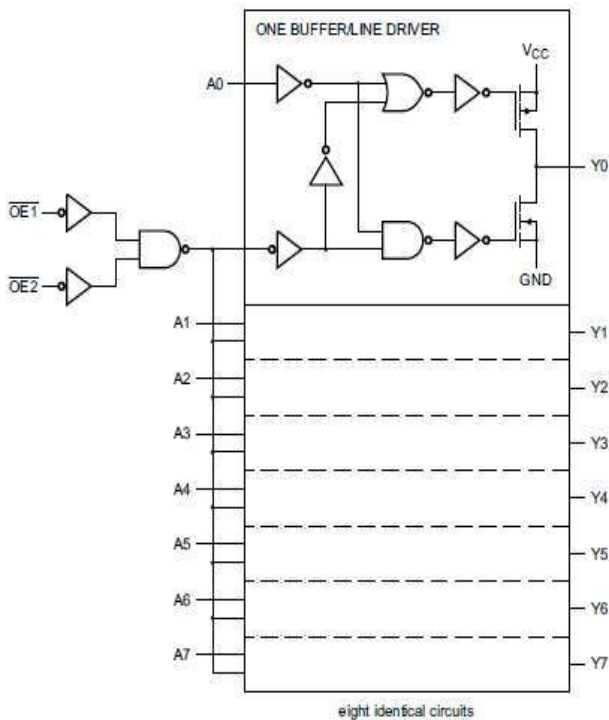
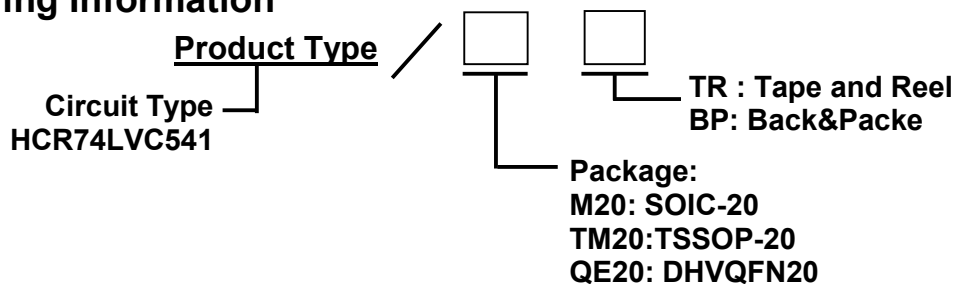


Figure 6. Logic Diagram

Octal Buffer/Line Driver; 3-State

Ordering Information



Ordering Code

Part Number	Marking	Temperature Range	Package	Quantity per Reel
HCR74LVC541/M20TR	HCR74LVC541	-40'C to +105'C	SOIC-20	2K/TR
HCR74LVC541/M20BP	HCR74LVC541	-40'C to +105'C	SOIC-20	2.8K/Box
HCR74LVC541/TM20TR	HCR74LVC541	-40'C to +105'C	TSSOP-20	4K/TR
HCR74LVC541/TM20BP	HCR74LVC541	-40'C to +105'C	TSSOP-20	14K/Box
HCR74LVC541/QE20TR	HCR74LVC541	-40'C to +105'C	DHVQFN20	3K/TR

Function Table

Input			Output
$\overline{OE1}$	$\overline{OE2}$	A_n	Y_n
L	L	L	L
L	L	H	H
X	H	X	Z
H	X	X	Z

Note: H=HIGH Voltage Level;

L=LOW voltage level; $\uparrow$ =LOW-to-HIGH clock transition;

X=don't care;

Z=HIGH-impedance OFF-state.

Octal Buffer/Line Driver; 3-State

ELECTRICAL PARAMETER Absolute Maximum Ratings

(Voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Supply Voltage	V _{CC}	-	-0.5	-	+6.5	V
Input Clamping Current	I _{IK}	V _I <0V	-50	-	-	mA
Input Voltage	V _I	-	-0.5	-	+6.5	V
Output Clamping Current	I _{OK}	V _O > V _{CC} or V _O < 0V	-	-	±50	mA
Output Voltage	V _O	Output High or Low	-0.5	-	V _{CC} +0.5	V
		Output 3-state	-0.5	-	6.5	
Output Current	I _O	V _O = 0V to V _{CC}	-	-	±50	mA
Supply Current	I _{CC}	-	-	-	100	mA
Ground Current	I _{GND}	-	-100	-	-	mA
Power Dissipation	P _{tot}	T _{amb} =-40 to +105°C; note 4	-	-	500	mW
Storage temperature	T _{stg}		-65	-	+150	°C
Soldering Temperature	T _L	10S	-	-	250	°C

Note 4: For SOP-20 packages: above 70°C the value of P_{tot} derates linearly with 8mW/K.

For TSSOP-20 packages: above 60°C the value of P_{tot} derates linearly with 5.5mW/K.

For DHVQFN20 packages: above 60°C the value of P_{tot} derates linearly with 4.5mW/K.

Recommended Operating Conditions

Parameter	Symbol	Conditions	Min.	Typ.	Max.	UNIT
Supply Voltage	V _{CC}	-	1.65	-	3.6	V
		functional	1.2	-	-	V
Input Voltage	V _I	-	0	-	5.5	V
Output Voltage	V _O	Output High or Low	0	-	V _{CC}	V
		Output 3-state	0	-	5.5	
Ambient temperature	T _{amb}	in free air	-40	-	+105	°C
Input transition rise and fall rate	Δt/ΔV	V _{CC} =2.3V to 2.7V	0	-	20	ns/V
		V _{CC} =2.7V to 3.6V	0	-	10	ns/V

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ELECTRICAL CHARACTERISTICS

DC Characteristics-1

(Tamb=-40' to +85'C, Voltages are referenced to GND(ground=0V), unless otherwise specified.)

Parameter	Symbol	Test Condition		Min	Type	Max	Unit
High Level Input Voltage	VIH	VCC=1.2V		1.08	-	-	V
		VCC=1.65V to 1.95V		0.65X VCC	-	-	
		VCC=2.3V to 2.7V		1.7	-	-	
		VCC=2.7V to 3.6V		2.0	-	-	
Low Level Input Voltage	VIL	VCC=1.2V		-	-	0.12	V
		VCC=1.65V to 1.95V		-	-	0.35X VCC	
		VCC=2.3V to 2.7V		-	-	0.7	
		VCC=2.7V to 3.6V		-	-	0.8	
High-Level Output Voltage	VOH	VI=VIH or VIL	IO=-100uA; VCC=1.65V to 3.6V	VCC-0.2	-	-	V
			IO=-4mA; VCC=1.65V	1.2	-	-	V
			IO=-8mA; VCC=2.3V	1.8	-	-	V
			IO=-12mA; VCC=2.7V	2.2	-	-	V
			IO=-18mA; VCC=3.0V	2.4	-	-	V
			IO=-24mA; VCC=3.0V	2.2	-	-	V
LOW-Level Output Voltage	VOL	VI=VIH or VIL	IO=100uA; VCC=1.65V to 3.6V	-	-	0.2	V
			IO=4mA; VCC=1.65V	-	-	0.45	V
			IO= 8mA; VCC=2.3V	-	-	0.6	V
			IO= 12mA; VCC=2.7V	-	-	0.4	V
			IO=-24mA; VCC=3.0V	-	-	0.55	V
Input Leakage Current	II	VCC=3.6V; VI=5.5V or GND		-	±0.1	±5	uA
OFF-state output current	IOZ	VCC=3.6V; VI=VIH or VIL, VO=5.5V or GND		-	±0.1	±5	uA
Power-off Leakage Current	IOFF	VCC=0V; VI or VO=5.5V		-	±0.1	±10	uA
Supply Current	ICC	VCC=3.6V; VI=VCC or GND; IO=0A		-	0.1	10	uA
additional supply current	ΔICC	per input pin; VCC=2.7V to 3.6V; VI=VCC-0.6V; IO=0A		-	5	500	uA
Input Capacitance	CI	-		-	5	-	pF

Note: 【1】 All typical values are measured at VCC=3.3V(unless stated otherwise) and Tamb=25'C.

Octal Buffer/Line Driver; 3-State

ELECTRICAL CHARACTERISTICS

DC Characteristics-2

(Tamb=-40' to +105'C, Voltages are referenced to GND(ground=0V), unless otherwise specified.)

Parameter	Symbol	Test Condition		Min	Type	Max	Unit
High Level Input Voltage	VIH	VCC=1.2V		1.08	-	-	V
		VCC=1.65V to 1.95V		0.65X VCC	-	-	
		VCC=2.3V to 2.7V		1.7	-	-	
		VCC=2.7V to 3.6V		2.0	-	-	
Low Level Input Voltage	VIL	VCC=1.2V		-	-	0.12	V
		VCC=1.65V to 1.95V		-	-	0.35X VCC	
		VCC=2.3V to 2.7V		-	-	0.7	
		VCC=2.7V to 3.6V		-	-	0.8	
High-Level Output Voltage	VOH	VI=VIH or VIL	IO=-100uA; VCC=1.65V to 3.6V	VCC-0.3	-	-	V
			IO=-4mA; VCC=1.65V	1.05	-	-	V
			IO=-8mA; VCC=2.3V	1.65	-	-	V
			IO=-12mA; VCC=2.7V	2.05	-	-	V
			IO=-18mA; VCC=3.0V	2.25	-	-	V
			IO=-24mA; VCC=3.0V	2.0	-	-	V
LOW-Level Output Voltage	VOL	VI=VIH or VIL	IO=100uA; VCC=1.65V to 3.6V	-	-	0.3	V
			IO=4mA; VCC=1.65V	-	-	0.65	V
			IO= 8mA; VCC=2.3V	-	-	0.8	V
			IO= 12mA; VCC=2.7V	-	-	0.6	V
			IO=-24mA; VCC=3.0V	-	-	0.8	V
Input Leakage Current	II	VCC=3.6V; VI=5.5V or GND		-	-	±20	uA
OFF-state output current	IOZ	VCC=3.6V; VI=VIH or VIL, VO=5.5V or GND		-	-	±20	uA
Power-off Leakage Current	IOFF	VCC=0V; VI or VO=5.5V		-	-	±20	uA
Supply Current	ICC	VCC=3.6V; VI=VCC or GND; IO=0A		-	-	40	uA
additional supply current	ΔICC	per input pin; VCC=2.7V to 3.6V; VI=VCC-0.6V; IO=0A		-	-	5000	uA

Note: 【1】 All typical values are measured at VCC=3.3V(unless stated otherwise) and Tamb=25'C.

Octal Buffer/Line Driver; 3-State

AC CHARACTERISTICS-1

(Tamb= -40°C to +85°C, voltages are referenced to GND (GND=0V); unless otherwise specified.)

Parameter	Symbol	Test Condition		Min	Type	Max	Unit
An to Yn Propagation Delay	tPd	See Figure 8	VCC=1.2V	-	14.0	-	ns
			VCC=1.65V to 1.95V	1.5	6.5	13.8	ns
			VCC=2.3V to 2.7V	1.0	3.5	6.8	ns
			VCC=2.7V	1.5	3.5	5.6	ns
			VCC=3.0V to 3.6V	1.0	2.9	5.1	ns
$\overline{\text{OEn}}$ to Yn enable time	ten	See Figure 9	VCC=1.2V	-	20	-	ns
			VCC=1.65V to 1.95V	1.8	7.7	16.0	ns
			VCC=2.3V to 2.7V	1.5	4.3	8.8	ns
			VCC=2.7V	1.5	4.4	7.5	ns
			VCC=3.0V to 3.6V	1.0	3.5	7.0	ns
n $\overline{\text{OE}}$ to Yn disable time	tdis	See Figure 9	VCC=1.2V	-	11.0	-	ns
			VCC=1.65V to 1.95V	3.0	4.9	10.3	ns
			VCC=2.3V to 2.7V	1.0	2.7	5.9	ns
			VCC=2.7V	1.5	3.7	7.0	ns
			VCC=3.0V to 3.6V	1.0	3.3	6.0	ns
Output Skew time	tSK(O)	-		-	-	1.0	ns
Power dissipation capacitance	CPD	per Input; Vi=GND to VCC	VCC=1.65V to 1.95V	-	7.7	-	pF
			VCC=2.3V to 2.7V	-	11.3	-	
			VCC=3.0V to 3.6V	-	14.4	-	

Note: [1] Typical values are measured at Tamb=25°C and VCC=1.8V, 2.5V, 2.7V and 3.3V respectively.

[2] tpd is the same as tPLH and tPHL.

ten is the same as tPZL and tPZH .

tdis is the same as tPLZ and tPHZ .

[3] Skew between any two outputs of the same package switching in the same direction.

This parameter is guaranteed by design.

[4] CPD is used to determine the dynamic power dissipation(PD in uW).

$PD = (CPD \times VCC^2 \times fi \times N) + \Sigma (CL \times VCC^2 \times fo)$ where:

fi=input frequency in MHz;

fo=output frequency in MHz;

CL=output load capacitance in pF;

VCC=supply voltage in Volt;

N=number of inputs switching;

$\Sigma (CL \times VCC^2 \times fo)$ =sum of outputs.

Octal Buffer/Line Driver; 3-State

AC CHARACTERISTICS-2

(Tamb= -40°C to +105°C, voltages are referenced to GND (GND=0V); unless otherwise specified.)

Parameter	Symbol	Test Condition		Min	Type	Max	Unit
An to Yn Propagation Delay	tPd	See Figure 4	Vcc=1.65V to 1.95V	1.5	-	16.0	ns
			Vcc=2.3V to 2.7V	1.0	-	7.9	ns
			Vcc=2.7V	1.5	-	7.0	ns
			Vcc=3.0V to 3.6V	1.0	-	6.5	ns
$\overline{\text{OEn}}$ to Yn enable time	ten	See Figure 5	Vcc=1.65V to 1.95V	1.8	-	18.5	ns
			Vcc=2.3V to 2.7V	1.5	-	10.2	ns
			Vcc=2.7V	1.5	-	9.5	ns
			Vcc=3.0V to 3.6V	1.0	-	9.0	ns
n $\overline{\text{OE}}$ to Yn disable time	tdis	See Figure 5	Vcc=1.65V to 1.95V	3.0	-	11.9	ns
			Vcc=2.3V to 2.7V	1.0	-	6.8	ns
			Vcc=2.7V	1.5	-	9.0	ns
			Vcc=3.0V to 3.6V	1.0	-	7.5	ns
Output Skew time	tSK(O)	-		-	-	1.5	ns

Note: [1] Typical values are measured at Tamb=25°C and VCC=1.8V, 2.5V, 2.7V and 3.3V respectively.

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

t_{en} is the same as t_{PZL} and t_{PHZ}.

t_{dis} is the same as t_{PLZ} and t_{PHZ}.

[3] Skew between any two outputs of the same package switching in the same direction.

This parameter is guaranteed by design.

Testing Circuit

AC Testing Circuit

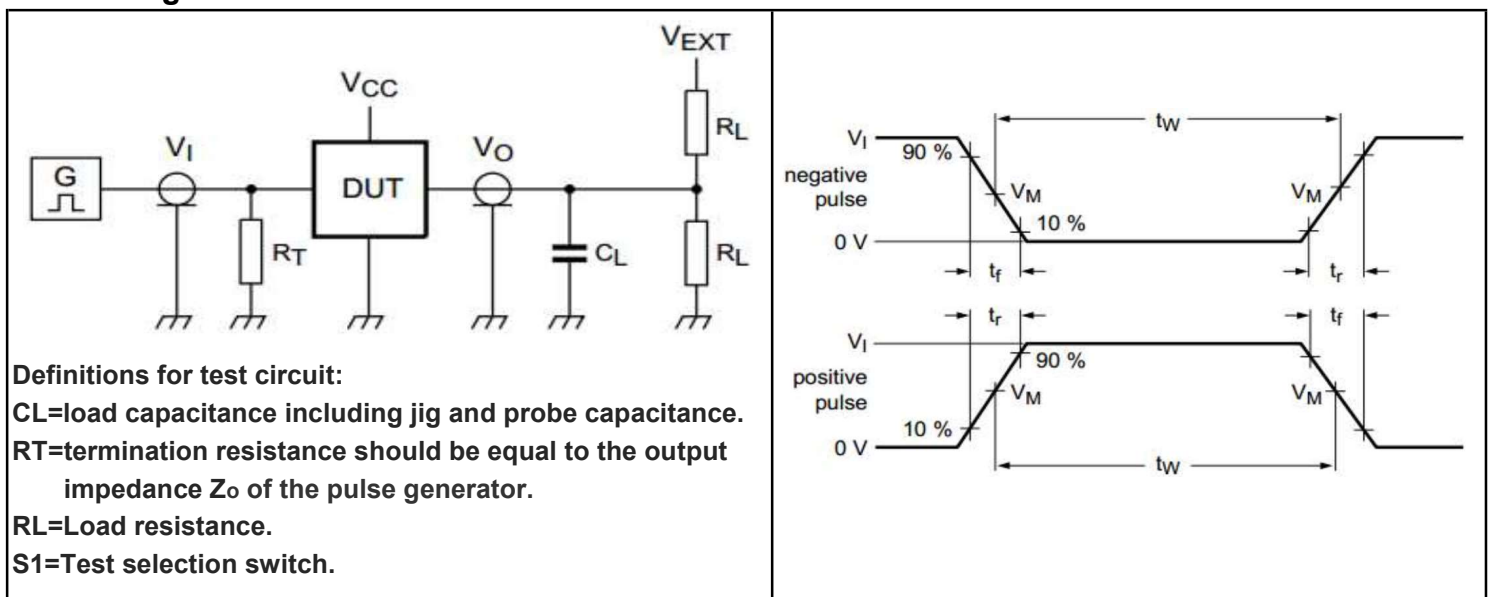


Figure 7. Test Circuit for Measuring Switching Times

Octal Buffer/Line Driver; 3-State

AC Testing Waveforms

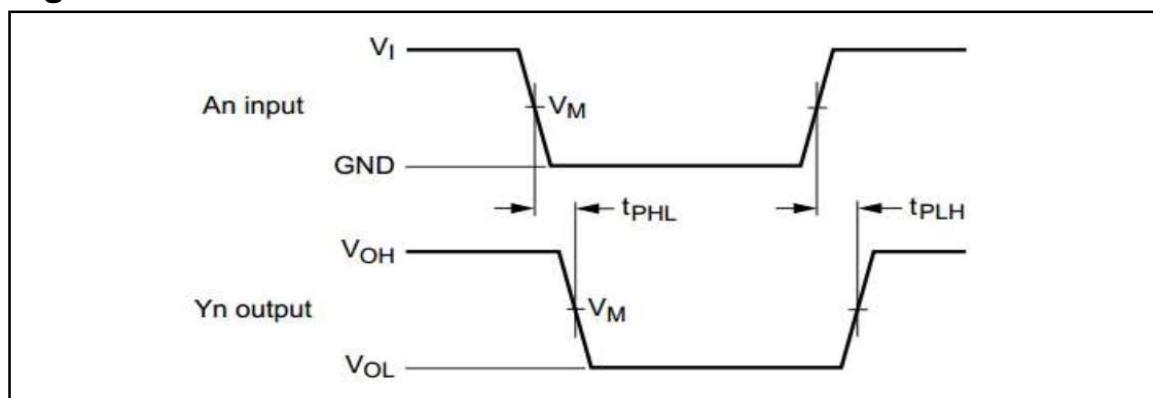


Figure 8. The input(An) to output (Yn) propagation delays

AC Testing Waveforms(Con.)

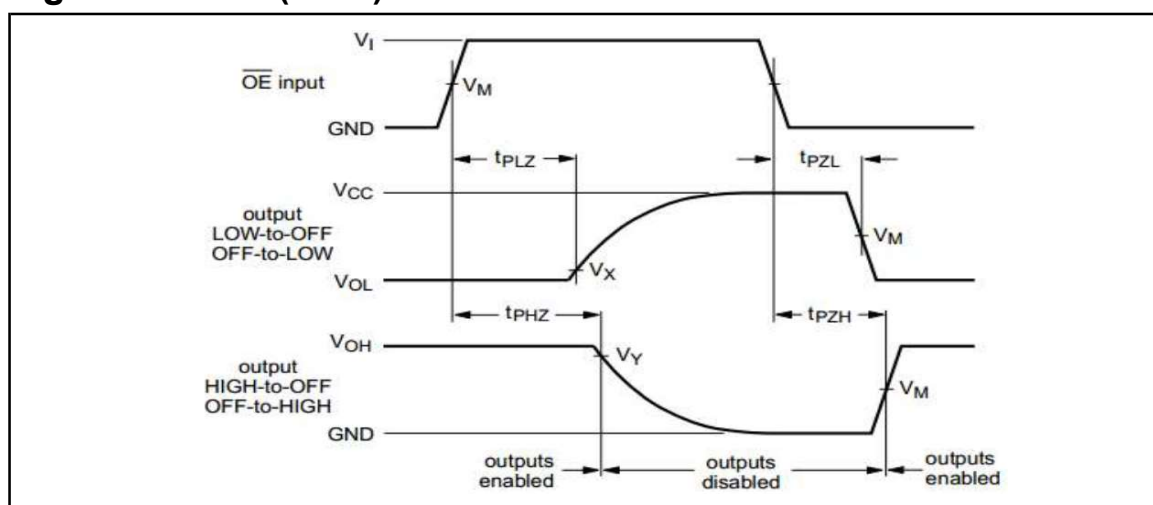


Figure 9. 3-state enable and disable times

Measurement Points

Supply Voltage	Input		Output		
VCC	VI	VM	VM	VX	VY
1.2V	VCC	0.5 X VCC	0.5 X VCC	VOL+0.15V	VOH-0.15V
1.65V to 1.95V	VCC	0.5 X VCC	0.5 X VCC	VOL+0.15V	VOH-0.15V
2.3V to 2.7V	VCC	0.5 X VCC	0.5 X VCC	VOL+0.15V	VOH-0.15V
2.7V	2.7V	1.5V	1.5V	VOL+0.3V	VOH-0.3V
3.0V to 3.6V	2.7V	1.5V	1.5V	VOL+0.3V	VOH-0.3V

Test Data

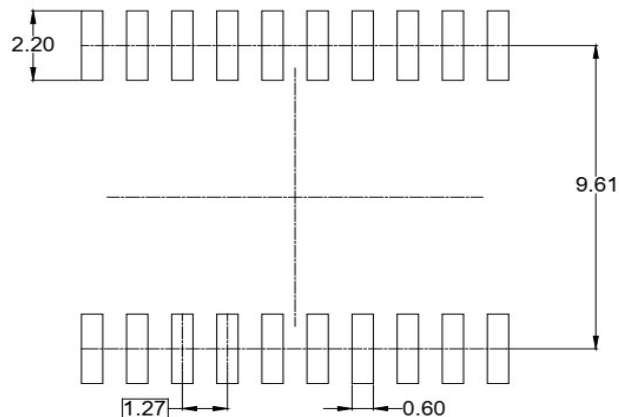
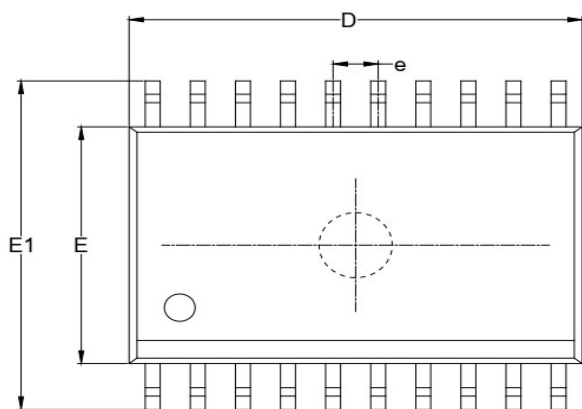
Supply Voltage	Input		Load		VEXT		
VCC	VI	tr, tf	CL	RL	tPLH, tPHL	tPZH, tPHZ	tPZL, tPLZ
1.2V	VCC	$\leq 2.0\text{ns}$	30pF	1K Ω	open	GND	2XVcc
1.65V to 1.95V	VCC	$\leq 2.0\text{ns}$	30pF	1K Ω	open	GND	2XVcc
2.3V to 2.7V	VCC	$\leq 2.0\text{ns}$	30pF	500 Ω	open	GND	2XVcc
2.7V	2.7V	$\leq 2.0\text{ns}$	50pF	500 Ω	open	GND	2XVcc
3.0V to 3.6V	2.7V	$\leq 2.0\text{ns}$	50pF	500 Ω	open	GND	2XVcc

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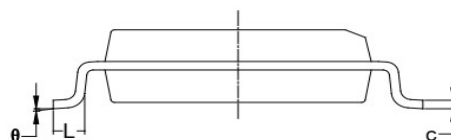
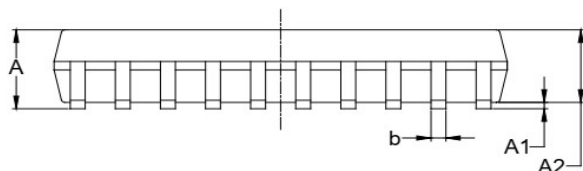
MECHANICAL DIMENSIONS.

PKG: SOIC-20 (M20)

Unit:mm



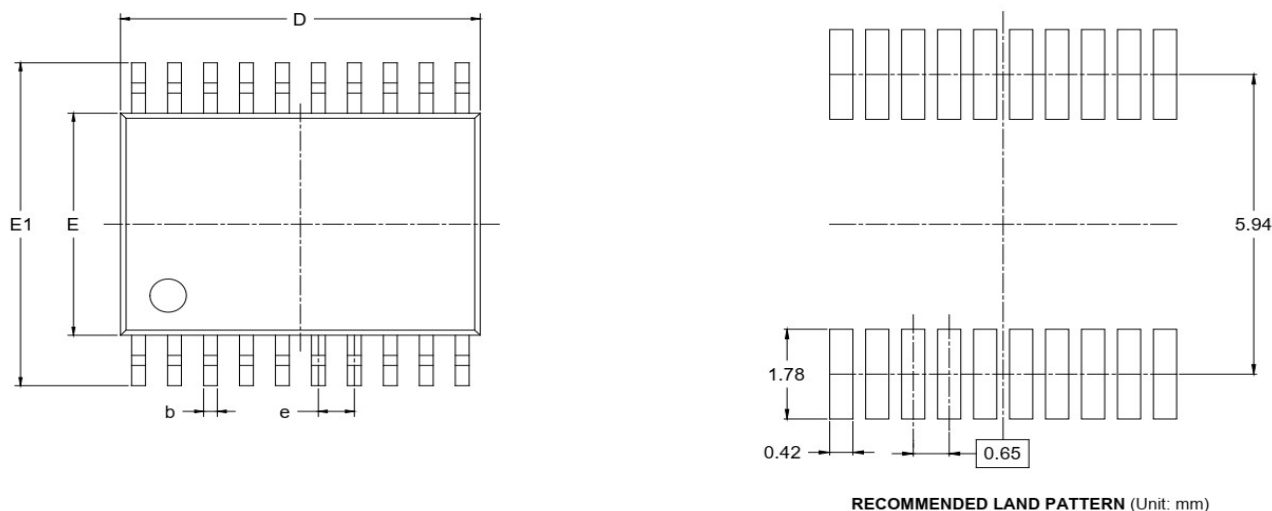
RECOMMENDED LAND PATTERN (Unit: mm)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	2.350	2.650	0.093	0.104
A1	0.100	0.300	0.004	0.012
A2	2.100	2.500	0.083	0.098
b	0.330	0.510	0.013	0.020
c	0.204	0.330	0.008	0.013
D	12.520	13.000	0.493	0.512
E	7.400	7.600	0.291	0.299
E1	10.210	10.610	0.402	0.418
e	1.27 BSC		0.050 BSC	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

NOTES:

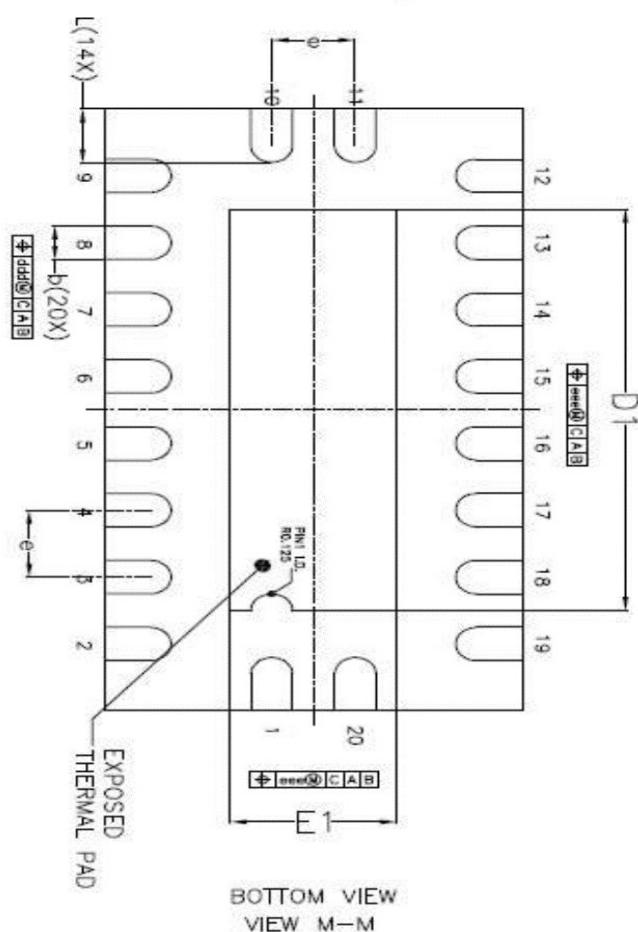
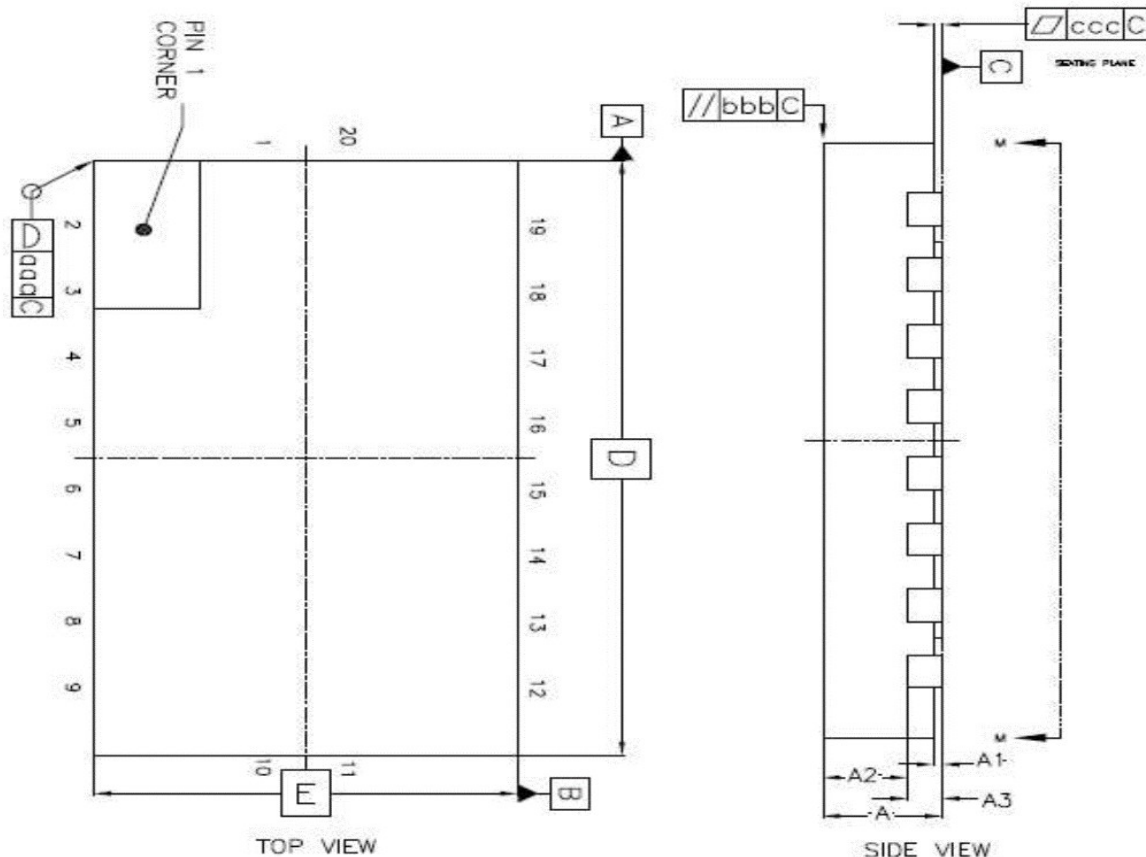
1. Body dimensions do not include mode flash or protrusion.
2. This drawing is subject to change without notice.

Octal Buffer/Line Driver; 3-State
MECHANICAL DIMENSIONS(Con.)
PKG: TSSOP-20 (TM20)
Unit:mm


Symbol	Dimensions In Millimeters		
	MIN	NOM	MAX
A	-	-	1.200
A1	0.050	-	0.150
A2	0.800	-	1.050
b	0.190	-	0.300
c	0.090	-	0.200
D	6.400	-	6.600
E	4.300	-	4.500
E1	6.200	-	6.600
e	0.650 BSC		
L	0.450	-	0.750
H	0.250 TYP		
θ	0°	-	8°
ccc	0.100		

NOTES:

1. Body dimensions do not include mode flash or protrusion.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-153.

Octal Buffer/Line Driver; 3-State
MECHANICAL DIMENSIONS(Con.)
PKG: DHVQF20 (QE20)
Unit:mm


DESCRIPTION		SYMBOL	MILLIMETER		
			MIN	NOM	MAX
TOTAL THICKNESS		A	0.80	0.85	1.00
STAND OFF		A1	0.00	0.02	0.05
MOLD THICKNESS		A2	0.60	0.65	0.70
L/F THICKNESS		A3	0.203 REF		
BODY SIZE	X	D	4.40	4.50	4.60
	Y	E	2.40	2.50	2.60
LEAD PITCH		e	0.50 BSC		
LEAD WIDTH		b	0.18	0.25	0.30
LEAD LENGTH		L	0.30	0.40	0.50
EP SIZE		D1	2.85	3.00	3.15
		E1	0.85	1.00	1.15
Tolerance of form and position					
aaa			0.1		
bbb			0.1		
ccc			0.05		
ddd			0.1		
eee			0.1		

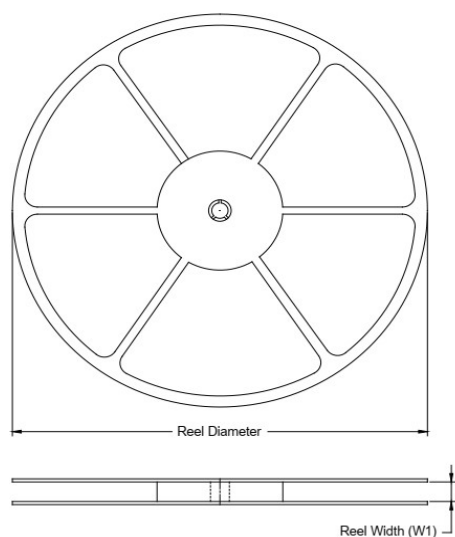
NOTES

1.0 COPLANARITY APPLIES TO LEADS, CORNER LEADS AND DIE ATTACH PAD.

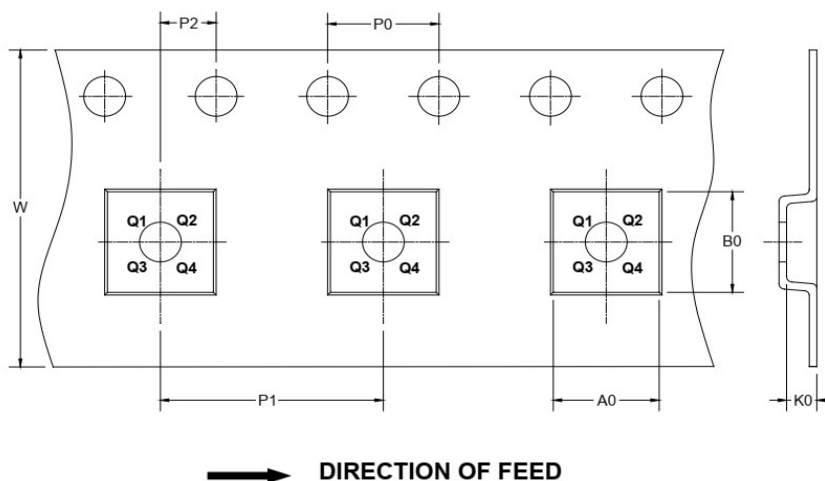
Octal Buffer/Line Driver; 3-State

TAPE AND REEL INFORMATION

REEL DIMENSIONS



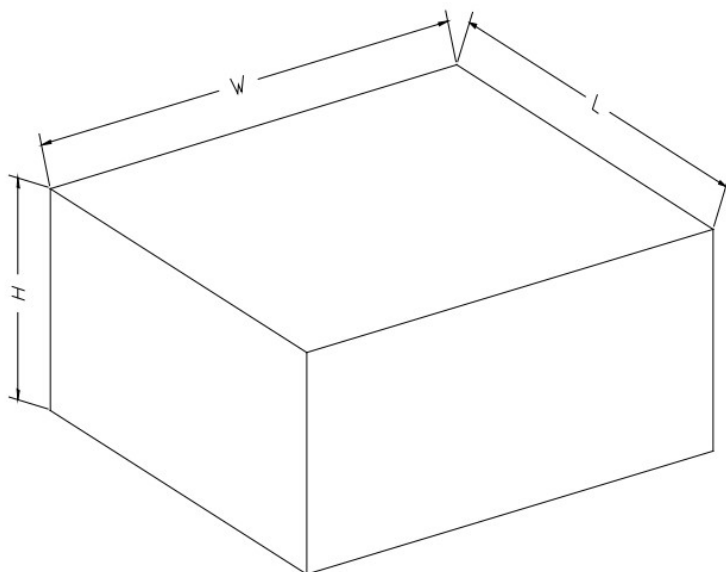
TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TSSOP-20	13"	16.4	6.80	6.90	1.50	4.0	8.0	2.0	16.0	Q1
SOIC-20	13"	24.4	10.90	13.30	3.00	4.0	12.0	2.0	24.0	Q1

Octal Buffer/Line Driver; 3-State**CARTON BOX DIMENSIONS**

NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
13"	386	280	370	5

Octal Buffer/Line Driver; 3-State

Statements And Notes

The name and content of Hazardous substances or Elements in the product

Part name	Hazardous substances or Elements									
	Lead and lead compounds	Mercury and mercury compounds	Cadmium and cadmium compounds	Hexavalent chromium compounds	Polybrominated biphenyls	Polybrominated biphenyl ethers	Dibutyl phthalate	Butylbenzyl phthalate	Di-2-ethylhexyl phthalate	Diisobutyl phthalate
Lead frame	o	o	o	o	o	o	o	o	o	o
Plastic resin	o	o	o	o	o	o	o	o	o	o
Chip	o	o	o	o	o	o	o	o	o	o
The lead	o	o	o	o	o	o	o	o	o	o
Plastic sheet installed	o	o	o	o	o	o	o	o	o	o
explanation	o: Indicates that the content of hazardous substances or elements in the detection limit of the following the SJ/T11363-2006 standard. X: Indicates that the content of hazardous substances or elements exceeding the SJ/T11363-2006 Standard limit requirements.									

Notion

Recommended carefully reading this information before the use of this product;

The information in this document are subject to change without notice;

This information is using to the reference only, the company is not responsible for any loss;

The company is not responsible for the any infringement of the third party patents or other rights of the responsibility.